

AM2362N-VB Datasheet

N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)		
60	0.030 at V _{GS} = 10 V	5.5	2.3 nC		
60	0.033 at V _{GS} = 4.5 V	4.5	2.5 110		

3 D

TO-236 (SOT23)

Top View

G 1

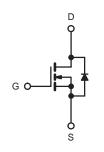
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FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested ٠
- 100 % UIS Tested

APPLICATIONS

- Battery Switch
- DC/DC Converter



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 2$	25 °C, unless oth	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	60	V	
Gate-Source Voltage	V _{GS}	± 20	v	
	T _C = 25 °C		5.5	
Continuous Drain Current (T ₁ = 150 °C)	T _C = 70 °C	I_	4.5	
Continuous Drain Current (1j = 100°C)	T _A = 25 °C	I _D	3.9 ^{b, c}	
	T _A = 70 °C		3.2 ^{b, c}	A
Pulsed Drain Current	I _{DM}	20	_ ^	
Continuous Source-Drain Diode Current	T _C = 25 °C	L.	1.39	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.91 ^{b, c}	
Avalanche Current	L = 0.1 mH	I _{AS}	6	
Single-Pulse Avalanche Energy		E _{AS}	1.8	mJ
	T _C = 25 °C	PD	1.66	
Maximum Power Dissipation	T _C = 70 °C		1.06	w
	T _A = 25 °C	' D	1.09 ^{b, c}	V
	T _A = 70 °C		0.7 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R _{thJA}	90	115	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	60	75	C/W

Notes:

a. Based on T_C = 25 °C. b. Surface Mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under Steady State conditions is 130 °C/W.



RoHS COMPLIANT HALOGEN FREE Available



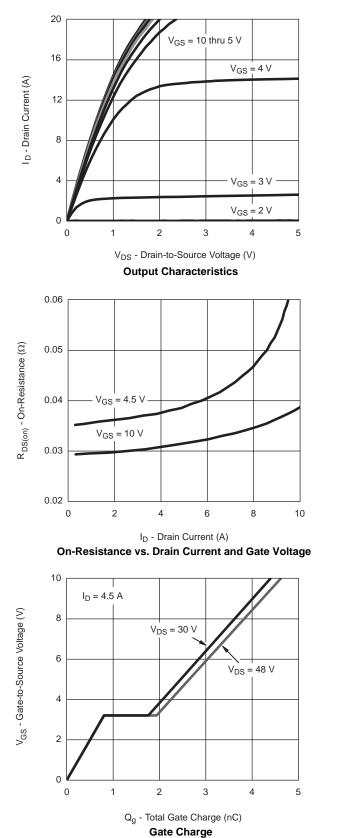
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-				1		
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			55		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μΑ		- 5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	1		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zana Oata Maltana Drain Ourrant	1	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, V_{GS} = 10 V	8			Α	
	D	V _{GS} = 10 V, I _D = 1.9 A		0.030			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 1.7 A		0.033		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15V, I _D = 1.9 A		5		S	
Dynamic ^b							
Input Capacitance	C _{iss}			190			
Output Capacitance	C _{oss}			26			
Reverse Transfer Capacitance	C _{rss}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		15		pF	
Total Gate Charge	Qg	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 1.9 \text{ A}$		4.5	6.8	-	
				2.3	3.5		
Gate-Source Charge	Q _{gs}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 1.9 \text{ A}$		0.8		nC	
Gate-Drain Charge	Q _{gd}			1		1	
Gate Resistance	Rg	f = 1 MHz	0.6	2.8	5.6	Ω	
Turn-On Delay Time	t _{d(on)}			4	6		
Rise Time	t _r	V_{DD} = 30 V, R_L = 20 Ω		10	15	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 1.5 A, V_{GEN} = 10 V, R_G = 1 Ω		10	15		
Fall Time	t _f			7	10.5		
Turn-On Delay Time	t _{d(on)}			15	23		
Rise Time	t _r	V_{DD} = 30 V, R_{L} = 20 Ω		16	24	ns	
Turn-Off Delay Time	t _{d(off)}	I_D = 1.5 A, V_{GEN} = 4.5 V, R_G = 1 Ω		11	17		
Fall Time	t _f			11	17		
Drain-Source Body Diode Characteristi	cs						
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			2.39	٨	
Pulse Diode Forward Current ^a	I _{SM}				8	A	
Body Diode Voltage	V _{SD}	I _S = 1.5 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			15	23	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			10	15	nC	
Reverse Recovery Fall Time	ta	$I_F = 1.5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{T}_J = 25 ^\circ\text{C}$		12		1	
Reverse Recovery Rise Time	t _b			3		ns	

Notes:

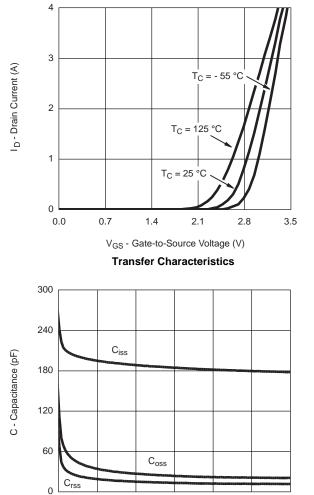
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

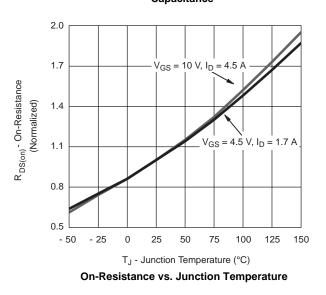




TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



V_{DS} - Drain-to-Source Voltage (V) Capacitance



服务热线:400-655-8788



I_D = 4.5 A

T_J = 125 °C

T_J = 25 °C

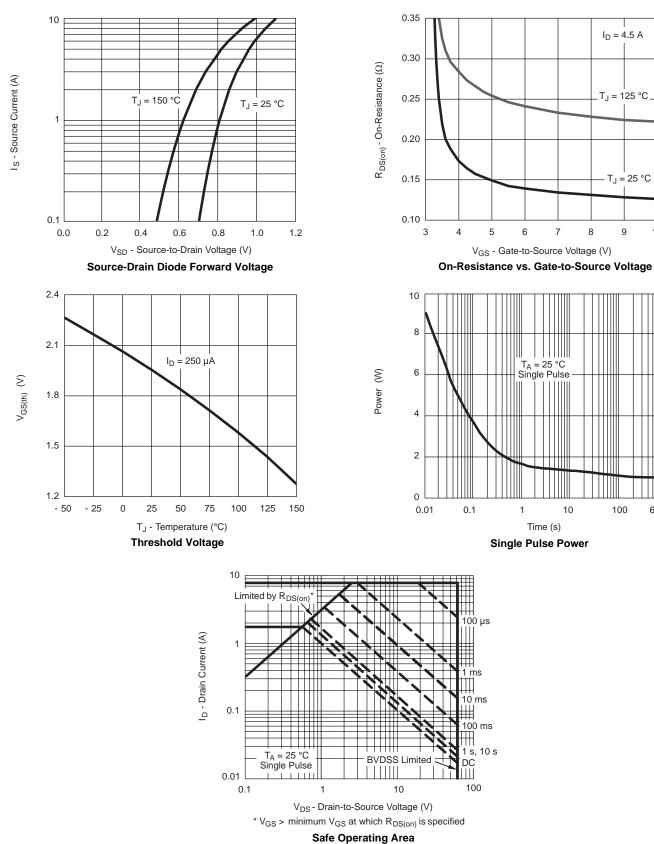
9

100

600

10

8

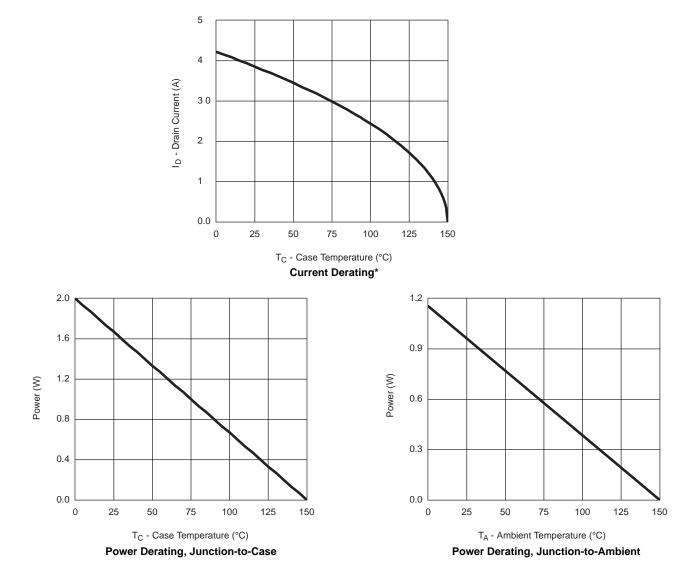


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



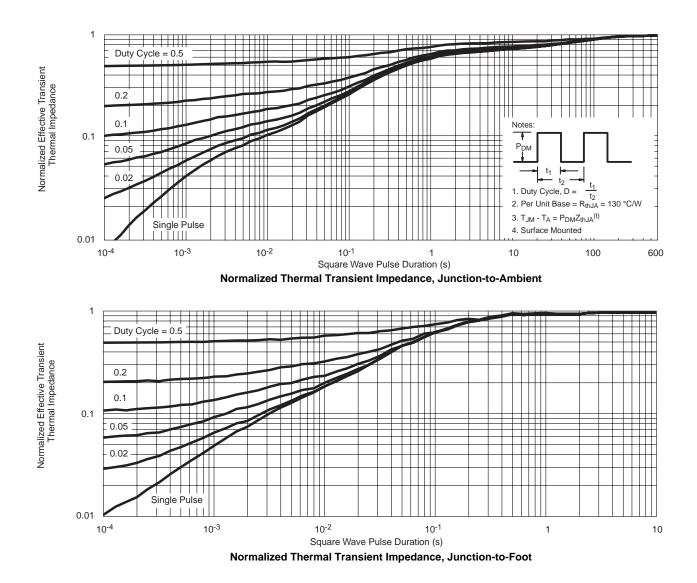


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



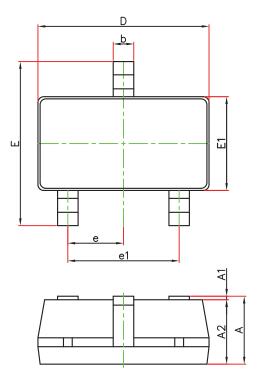


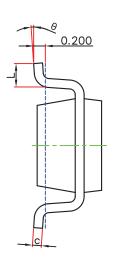
THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)

AM2362N-VB



SOT-23-3L



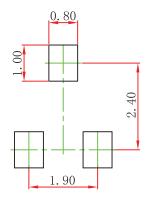


Symbol	Dimensions In	n Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
E	2.650	2.950	0.104	0.116	
е	0.950(0.950(BSC)		(BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

AM2362N-VB



RECOMMENDED MINIMUM PADS FOR SOT-23-3L



Note:

Controlling dimension:in millimeters.
General tolerance:±0.05mm.
The pad layout is for reference purposes only.



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